



## Material Content Data Sheet



<b>Sales Product Name</b>		IPL60R199CP		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001256474						
<b>Package</b>		PG-VSON-4-1		<b>Weight*</b>		190.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.809	4.62	4.62	46190	46190
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		67	
	non noble metal	zinc	7440-66-6	0.051	0.03		267	
	non noble metal	iron	7439-89-6	1.017	0.53		5333	
wire	non noble metal	copper	7440-50-8	41.300	21.66	22.23	216555	222222
	non noble metal	copper	7440-50-8	1.001	0.52	0.52	5248	5248
	encapsulation	organic material	carbon black	1333-86-4	0.210	0.11		1099
plastics	plastics	epoxy resin	-	10.791	5.66		56581	
	inorganic material	silicondioxide	60676-86-0	93.766	49.16	54.93	491653	549333
	non noble metal	tin	7440-31-5	2.397	1.26	1.26	12571	12571
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1321	1321
solder	noble metal	silver	7440-22-4	0.151	0.08		793	
	non noble metal	tin	7440-31-5	0.121	0.06		635	
	non noble metal	lead	7439-92-1	5.779	3.03	3.17	30304	31732
heatspreader	inorganic material	phosphorus	7723-14-0	0.008	0.00		39	
	non noble metal	zinc	7440-66-6	0.030	0.02		158	
	non noble metal	iron	7439-89-6	0.601	0.32		3153	
	non noble metal	copper	7440-50-8	24.418	12.80	13.14	128033	131383
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com